Semiconductor Device Type: **C5X-TSSOP-8-3x4.4x1.2mm-MatteTin**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Mold Compound	Epoxy Resin A	Trade Secret	4.13	1.36	41342
Mold Compound	Epoxy Resin B	Trade Secret	1.18	0.39	11812
Mold Compound	Phenol Resin	Trade Secret	1.18	0.39	11812
Mold Compound	Silica (Amorphous)	60676-86-0	51.97	17.15	519728
Mold Compound	Carbon Black	1333-86-4	0.59	0.19	5906
Lead Frame	Copper	7440-50-8	29.91	9.87	299125
Lead Frame	Nickel	7440-02-0	0.95	0.31	9456
Lead Frame	Silicon	7440-21-3	0.32	0.10	3152
Lead Frame	Magnesium	7739-95-4	0.03	0.01	315
Lead Frame	Silver	7440-22-4	0.32	0.10	3152
Die Attach	Silver	7440-22-4	1.08	0.35	10752
Die Attach	Epoxy Resin	Trade Secret	0.01	0.00	112
Die Attach	Cashew, nutshell liq. polymer with epichlorohydrin	68413-24-1	0.01	0.00	112
Die Attach	Toluene	108-88-3	0.01	0.00	112
Die Attach	2-Heptyl-3,4-bis(9-isocyanatononyl)-1-pentylcyclohexane	68239-06-5	0.01	0.00	56
Die Attach	1,1'-(methylenedi-p-phenylene)bismaleimide	13676-54-5	0.01	0.00	56
Die	Silicon	7440-21-3	6.30	2.08	63000
Bonding Wire	Gold	7440-57-5	0.18	0.06	1800
Plating on External Leads	Tin	7440-31-5	1.82	0.60	18191
Plating on External Leads	Lead	7439-92-1	0.00	0.00	9
		TOTALS:	100.00	33.00	1,000,000

33.00 mg Total Mass

	Package Homogeneous Materials			
19.49	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**59.06**
	Epoxy Resin A	Trade Secret	7.00	
	Epoxy Resin B	Trade Secret	2.00	
	Phenol Resin	Trade Secret	2.00	
	Silica (Amorphous)	60676-86-0	88.00	
	Carbon Black	1333-86-4	1.00	
		Total	**100.00**	
10.40	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**31.52**
	Copper	7440-50-8	94.90	
	Nickel	7440-02-0	3.00	
	Silicon	7440-21-3	1.00	
	Magnesium	7739-95-4	0.10	
	Silver	7440-22-4	1.00	
		Total	**100.00**	
0.37	**(mg) Total**	**Die Attach**	**% of Total Weight**	**1.12**
	Silver	7440-22-4	96.00	
	Epoxy Resin	Trade Secret	1.00	
	Cashew, nutshell liq. polymer with epichlorohydrin	68413-24-1	1.00	
	Toluene	108-88-3	1.00	
	2-Heptyl-3,4-bis(9-isocyanatononyl)-1-pentylcyclohexane	68239-06-5	0.50	
	1,1'-(methylenedi-p-phenylene)bismaleimide	13676-54-5	0.50	
		Total	**100.00**	
2.08	**(mg) Total**	**Die**	**% of Total Weight**	**6.30**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
0.06	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**0.18**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
0.60	**(mg) Total**	**Plating on External Leads**	**% of Total Weight**	**1.82**
	Tin	7440-31-5	99.95	
	Lead	7439-92-1	0.05	
33.00		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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